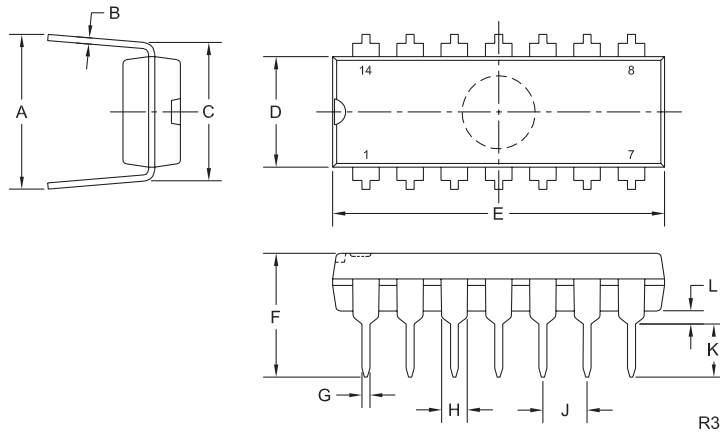


# Package Details - TO-116

## Mechanical Drawing



SYMBOL	DIMENSIONS			
	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.310	0.390	7.9	9.9
B	0.008	0.014	0.2	0.4
C	0.310		7.9	
D	0.240	0.260	6.1	6.6
E	0.740	0.760	18.8	19.3
F	-	0.300	-	7.6
G	0.014	0.022	0.4	0.6
H	0.050		1.3	
J	0.100		2.5	
K	0.125	0.150	3.2	3.8
L	0.015	-	0.4	-

TO-116 (REV: R3)

### Packing options:

#### Bulk - Packing Code: C

C = Antistatic coated plastic sleeves (surface resistivity of  $>10^9$  and  $<10^{13}$  ohms per square).

Bulk Packing Quantity: 25

# Material Composition Specification

TO-116 Case

Available with Pb (lead)-free plating\*



Device average mass .....1035 mg  
Fluctuation margin ..... +/-10%

Device part	Substance	mass (mg)
active device	doped Si	0.60
bond wire	Au	0.20
leadframe	Cu alloy	338
leadframe plating	Ag	1.93
die attach	silver epoxy - Ag 75% - epoxy resin 25%	0.27
*plating	SnPb20 or Sn (100% tin, Pb-free)	12.0 12.0
encapsulation	partially brominated epoxy -silica 80% -resin (phenolix and epoxy) < 15% -Sb <sub>2</sub> O <sub>3</sub> < 2.0% -TBBA < 2.5% -carbon < 0.50%	682

\* specify Lead-free when ordering 100% tin (Pb-free) plating option.